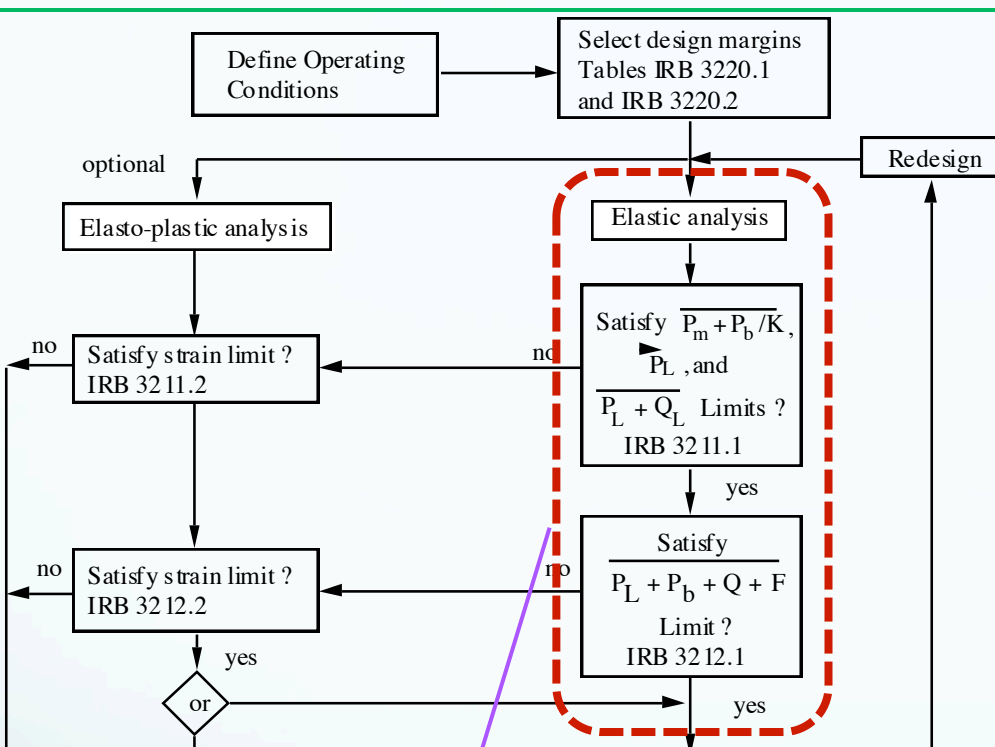


# Analysis Flow Chart for Low-Temperature SDC-IC Design Rules for Given Operating Conditions



- $PM + Pb/K$  = creep damage limit
- $PL$  = immediate Plastic collapse and plastic instability
- $PL + QL$  = Plastic Flow Localization
- $PL + PB + Q + F$  = ductility exhaustion limit

- Brittle Fracture:  
 $K_I$  = stress intensity factor ( $a = h/4$ ),
- 3Sm ratcheting due to cyclic loading limit

